

**REMARKS**

Claim 1 has been amended to make it clear that it does not matter whether the integrated inductor is formed on the substrate first or the aperture is formed in the substrate first, so long as the aperture ends up underneath the inductor.

Respectfully requested,

Date:

6/12/02



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## APPENDIX

### IN THE CLAIMS

Please amend claim 1 as follows:

1 (Amended). A method comprising:

forming an integrated inductor over a substrate;

forming an aperture [underneath said inductor] through said substrate from  
the back side of said substrate so that said aperture is located under said inductor; and

filling said aperture with a dielectric material.

Please add the following new claim:

21 (New). The method of claim 1 including forming said aperture under said  
inductor.

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JUN 26 2002  
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